



*[Handwritten signature]*  
**PATENT**  
*[Handwritten initials]*

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:** John W. Ladd

**Serial No.:** 10/035,738

**Filed:** November 7, 2001

**For:** APPARATUS FOR ESTABLISHING  
AN ELECTRICAL CONNECTION WITH A  
WAFER TO FACILITATE WAFER-LEVEL  
BURN-IN AND METHODS

**Examiner:** R. Chang

**Group Art Unit:** 2833

**Attorney Docket No.:** 2269-4584.1US  
(00-0787.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 10, 2003  
Date

*[Signature]*  
Signature

Deidra Pfeil

Name (Type/Print)

AMENDMENT

Commissioner for Patents  
Mail Stop Non-Fee Amendment  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of July 10, 2003, the initial period for response to which expires on October 10, 2003.

**Amendments to the Title** appear on page 2 of this paper;

**Amendments to the Abstract** are on page 3 of this paper;

**Amendments to the Claims** are set forth in the listing of the claims, which begins on page 4 of this paper; and

**Remarks** start at page 7 of this paper.

**RECEIVED**  
OCT 21 2003  
TECHNOLOGY CENTER R3700

IN THE TITLE:

Please amend the title, which appears on the cover page and at the top of page 2 of the above-referenced application, as follows:

**APPARATUS METHODS FOR MAGNETICALLY ESTABLISHING AN ELECTRICAL**  
**CONNECTION WITH A CONTACT OF A SEMICONDUCTOR DEVICE**  
**COMPONENT** ~~WAFER TO FACILITATE WAFER-LEVEL BURN-IN AND METHODS~~